

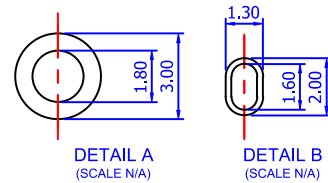
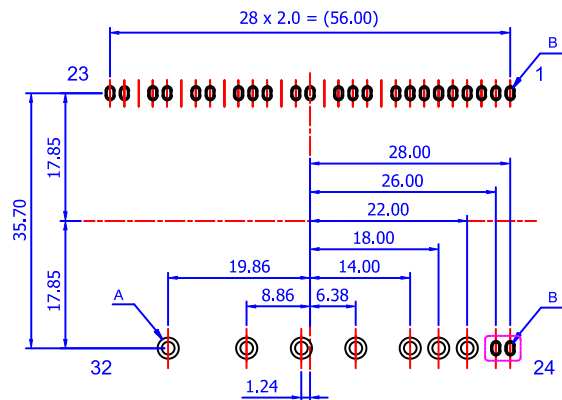
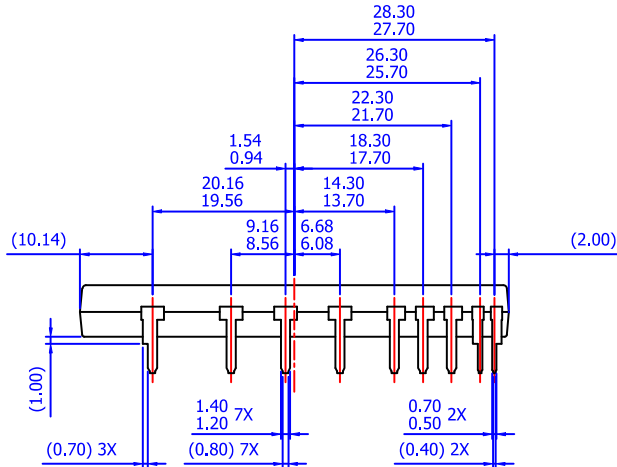
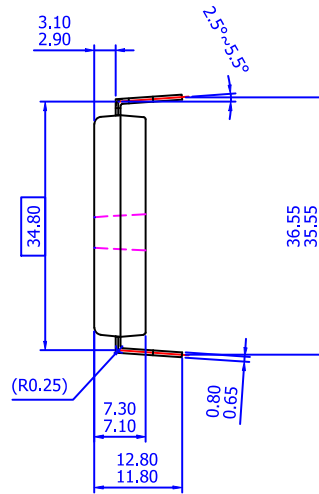
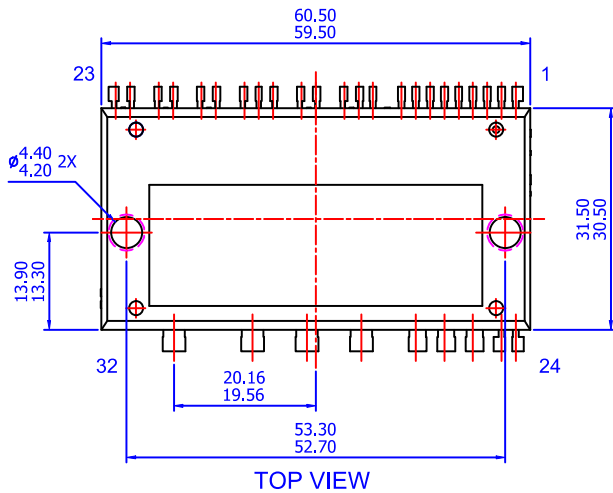
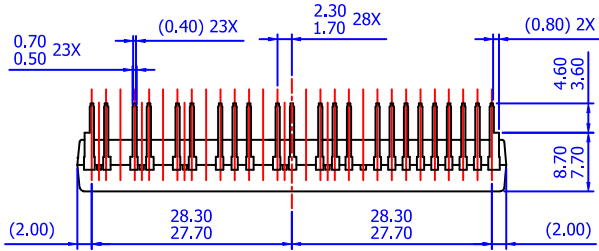
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



## S32AA-032 / 32LD, PDD STD, CERAMIC DIP TYPE CASE MODDV ISSUE O

DATE 31 DEC 2016



### LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.  
 D) ( ) IS REFERENCE

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